

INTERNATIONAL STANDARD

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**Field Device Integration (FDI)[®] –
Part 103-4: PROFINET**

**Intégration des appareils de terrain (FDI)[®] –
Partie 103-4: PROFINET**





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IEC Secretariat
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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IEC 62769-103-4

Edition 3.0 2023-04

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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 25.040.40; 35.100.05

ISBN 978-2-8322-6821-6

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CONTENTS

FOREWORD..... 4

1 Scope..... 6

2 Normative references 6

3 Terms, definitions, abbreviated terms and acronyms 7

 3.1 Terms and definitions..... 7

 3.2 Abbreviated terms and acronyms 7

4 Conventions 7

 4.1 EDDL syntax..... 7

 4.2 XML syntax..... 7

 4.3 Capitalizations 7

5 Profile for PROFINET 8

 5.1 General..... 8

 5.2 Catalog profile 8

 5.2.1 Protocol support file..... 8

 5.2.2 CommunicationProfile definition..... 9

 5.2.3 Profile device..... 9

 5.2.4 Protocol version information 9

 5.3 Associating a Package with a device..... 10

 5.3.1 Device type identification mapping..... 10

 5.3.2 Device type revision mapping 11

 5.4 Information Model mapping 12

 5.4.1 ProtocolType definition 12

 5.4.2 DeviceType mapping 13

 5.4.3 FunctionalGroup identification definition 13

 5.5 Topology elements..... 14

 5.5.1 ConnectionPoint definition 14

 5.5.2 Communication Device definition 15

 5.5.3 Communication service provider definition 16

 5.5.4 Network definition 17

 5.6 Methods..... 17

 5.6.1 Methods for FDI[®] Communication Servers 17

 5.6.2 Methods for Gateways 21

Annex A (normative) Topology scan schema..... 29

 A.1 General..... 29

 A.2 Target Namespace..... 29

 A.3 Network 29

 A.4 ProfinetNetworkT 29

 A.5 ProfinetConnectionPointT 30

 A.6 ProfinetIdentificationT 30

 A.7 MACT 32

 A.8 IPv4T..... 32

 A.9 IPv6T..... 32

 A.10 DNSNameT..... 32

 A.11 Hex4DigitT..... 32

Annex B (normative) Transfer service parameters..... 33

 B.1 General..... 33

B.2	Target Namespace.....	33
B.3	sendData	33
B.4	receiveData	33
B.5	TransferSendDataT.....	33
B.6	TransferResultDataT.....	34
B.7	OperationT.....	35
Annex C (informative)	Mapping to PA DIM	36
C.1	General.....	36
C.2	Mapping table	36
Bibliography	37
Figure 1	– Version mapping problem.....	11
Table 1	– ProtocolSupportFile for FDI® Device Packages.....	9
Table 2	– ProtocolSupportFile for FDI® Communication Packages	9
Table 3	– Catalog values for profile devices.....	9
Table 4	– Version mapping examples.....	10
Table 5	– Device identification information mapping.....	11
Table 6	– Protocol type Profinet_IO	12
Table 7	– DeviceType Property mapping.....	13
Table 8	– PROFINET identification type definition.....	13
Table 9	– ConnectionPoint type for Profinet_IO	14
Table 10	– Method Connect arguments.....	18
Table 11	– Method Disconnect arguments	19
Table 12	– Method Transfer arguments.....	20
Table 13	– Method SetAddress arguments.....	21
Table 14	– Method Connect arguments.....	23
Table 15	– Method Transfer arguments.....	24
Table 16	– Method SetAddress arguments.....	26
Table A.1	– Elements of ProfinetNetworkT	29
Table A.2	– Attributes of ProfinetConnectionPointT	30
Table A.3	– Elements of ProfinetConnectionPointT	30
Table A.4	– Attributes of ProfinetIdentificationT	31
Table B.1	– Attributes of TransferSendDataT.....	34
Table B.2	– Attributes of TransferResultDataT	34
Table C.1	– Mapping from PN standard parameters to PA DIM	36

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IEC 62769-103-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2020. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DeviceType to ProfinetIdentificationT;
- b) added namespace to Annex A and Annex B;
- c) added mapping rule for Device type when running in profile mode;
- d) replaced GSD file with GSDML file, detailing of device type mapping;
- e) added mapping to PA DIM.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/863/CDV	65E/920/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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